

INFORMATION DISCLOSURE CITATION PTO-1449	Atty. Docket No. 980404A	Serial No. Not Yet Assigned
	Applicant(s): Kazuhisa TSUNOI et al.	
	Filing Date: March 14, 2001	Group Art Unit: Not Yet Assigned

09/805559
03/14/01

U.S. PATENT DOCUMENTS

Examiner Initial	Document No.	Name	Date	Class	Subclass	Filing Date (If appropriate)
<u>JN</u>	AA	4,442,966	Jourdain et al.	4/17/84		
<u>JN</u>	AB	5,706,579	Ross	1/1998		
<u>JN</u>	AC	5,245,750	Crumly et al.	9/1993		
<u>JN</u>	AD	5,545,589	Tomura et al	8/1996		
<u>JN</u>	AE	5,783,465	Canning et al	7/1998		
<u>JN</u>	AF	5,403,424	Ehrat et al	4/1995		
	AG					

FOREIGN PATENT DOCUMENTS

Document No.	Date	Country	Translation (Yes or No)
<u>JN</u> AH 07-193101	7/28/95	Japan	Yes (Abstract)
<u>JN</u> AI EP 0 753 890 A2	1/15/97	European	Yes
<u>JN</u> AJ EP 0 724 289 A2	7/31/96	European	Yes
<u>JN</u> AK EP 0 596 393 A1	5/11/94	European	Yes
<u>JN</u> AL EP 0 388 011 A2	9/19/90	European	Yes
<u>JN</u> AM WO 96/05614	2/22/96	PCT	Yes
<u>JN</u> AN JP 6-302649	10/28/94	Japan	
<u>JN</u> AO JP 7-161769	6/23/96	Japan	
<u>JN</u> AP 6-151505	5/1994	Japan	
<u>JN</u> AQ 5-315395	11/1993	Japan	
AR			

INFORMATION DISCLOSURE CITATION PTO-1449	Atty. Docket No. 980404A	Serial No. Not Yet Assigned
	Applicant(s): Kazuhisa TSUNOI et al.	
	Filing Date: March 14, 2001	Group Art Unit: Not Yet Assigned

OTHER DOCUMENTS

<u>JN</u>	AS	Yoshihiro Bessho et al. "A Stud-Bump-Bonding Technique For High Density Multi-Chip-Module" Proceedings of the Japan International Electric Manufacturing Technology Symposium, US, New York, IEEE, vol. SYMP. 14, 1993, pps 326-365
<u>JN</u>	AT	Copy of European Patent Office Communication for European Patent Application No. 98302110 including European Search Report dated February 21, 2000.
<u>JN</u>	AU	"Nomenclature For the Adhesive Industry" 1-1959, pp. 1-2 (156/325)
Examiner <u>JOSEPH NGUYEN</u> Date Considered <u>10/20/01</u>		

U.S. PAT. & TM. OFF.
09/805559
03/14/01